## **Specifications**

Drawing No.	UKY1C-H1-16225-00[43] 1/12
Issued Date.	Mar,2,2016

# TO: Digi-Key

Note: In case of specification change, KYOCERA Part Number also will be changed.

Product Name	Quartz Crystal		
Product Model	CX3225SB		
Frequency	Refer to UKY1C-H1-16225-00[43] 3/12 Nominal Frequency		
Customer Part Number	-		
Customer Specification Number	-		
KYOCERA Part Number	Refer to UKY1C-H1-16225-00[43] 3/12 Nominal Frequency		
Remarks Pb-Free, RoHS Compliant, MSL 1			

#### Customer Acceptance

Accept Signature	Approved Date	
	Department	
	-	
	Person in charge	

#### Seller

### **KYOCERA Crystal Device Corporation**

(Sales Division) 6 Takeda Tobadono-cho, Fushimi-ku, Kyoto 612-8501 Japan TEL. No. 075-604-3500 FAX. No. 075-604-3501

#### Manufacturer

Crystal Units Division 5850, Higashine-Koh, Higashine-Shi, Yamagata 999-3701 Japan TEL. No. 0237-43-5611 FAX. No. 0237-43-5615

Design Department	Quality Assurance	Approved by	Checked by	Issued by
KYOCERA Crystal Device Corporation Crystal Units Engineering Section Crystal Units Division	T. Noritake	Y. Takahashi	T. Nitoube	Y. Kikuchi

Drawing No.	UKY1C-H1-16225-00[43]	2/12
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## **Revision History**

Rev.No.	Description of revise	Date	Approved by	Checked by	Issued by
1	First Edition	Mar,2,2016	Y. Takahashi T. Nitoube		Y. Kikuchi

## [PART NUMBER LIST]

Nominal Frequency (MHz)	KYOCERA Part Number	ESR (Ω)	Nominal Frequency Code
12	CX3225SB12000H0PSTC1	150	12000
16	CX3225SB16000H0PSTC1	80	16000
20	CX3225SB20000H0PSTC2	50	20000
24	CX3225SB24000H0PSTC1	50	24000

#### **1. APPLICATION**

This specification sheet is applied to quartz crystal "CX3225SB"

#### 2. KYOCERA PART NUMBER

Refer to UKY1C-H1-16225-00[43] 3/12 KYOCERA Part Number

#### **3. RATINGS**

Items	SYMB.	Rating	Unit	Remarks
Operating Temperature	Topr	-40 to +125	°C	
Storage Temperature range	Tstg	-40 to +125	C	

### 4. CHARACTERISTICS

#### **ELECTRICAL CHARACTERISTICS**

Items		Electrical Specification			Test Condition	Remarks	
	SYMB.	Min	Тур.	Max	Unit		
Mode of Vibration			Fundamental				
Nominal Frequency	F0		<b>※1</b>		MHz		
Nominal Temperature	T <sub>NOM</sub>		+25		°C		
Load Capacitance	CL		12.0		pF		
Frequency Tolerance	df/F	-50.0		+50.0		+25±3°C	
Frequency Temperature characteristics	df/F	-100.0		+100.0	PPM	-40 to +125°C	
Frequency Aging Rate		-1.0		+1.0		1 <sup>st</sup> year	+25±3℃
Equivalent Series Resistance	ESR			<b>※</b> 2	Ω		
Drive Level	Pd	0.01		100	μW		
Insulation Resistance	IR	500			MΩ	100V(DC)	

%1 Refer to UKY1C-H1-16225-00[43] 3/12 Nominal Frequency%2 Refer to UKY1C-H1-16225-00[43] 3/12 ESR

#### 5. Measurement Condition

Drive Level

5.1 Frequency measurement

Measuring instrument : IE	EC PI-Network Test Fixture
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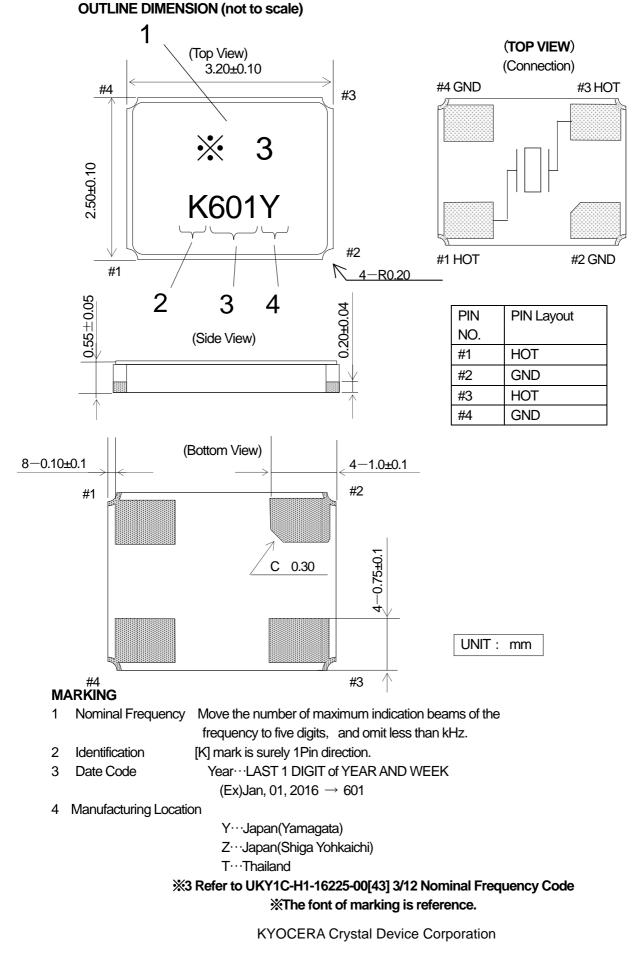
- Load Capacitance : 12.0pF
  - : 10µW

#### 5.2 Equivalent series resistance (ESR) measurement

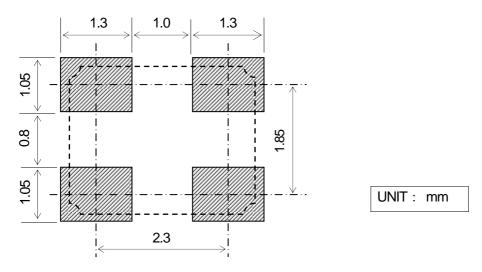
Measuring instrument : IEC PI-Network Test Fixture

Load Capacitance : Series : 10µW

Drive Level

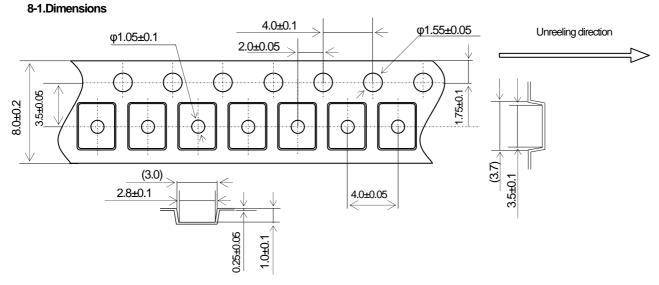


## 6. APPEARANCES, PHYSICAL DIMENSION

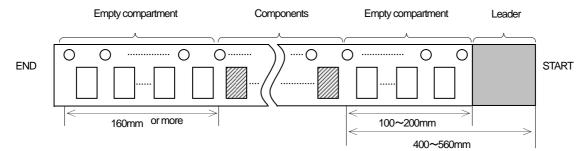


## 7. RECOMMENDED LAND PATTERN (not to scale)

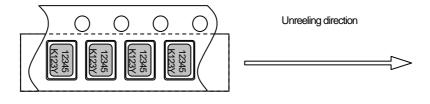
#### **8.TAPING & REEL**



#### 8-2.Leader and trailer tape



#### 8-3.Direction (The direction shall be seen from the top cover tape side)



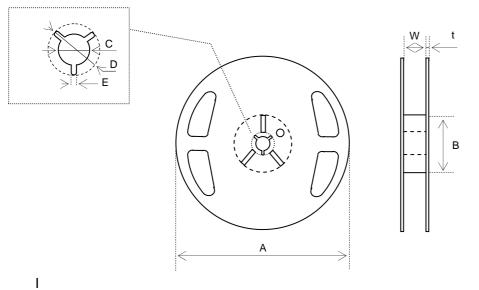
#### 8-4.Specification

- 1. Material of the carrier tape is either polystyrene or A-PET (ESD).
- 2. Material of the cover tape is polyester (ESD).
- 3. The seal tape shall not cover the sprocket holes and not protrude from the carrier tape.
- 4. Tensile strength of carrier tape: 10N or more.
- 5. The R of the corner of each cavity is 0.2RMAX.
- 6. The alignment between centers of the cavity and sprocket hole shall be 0.05mm or less.
- 7. The orientation shall be checked from the top cover tape side as shown in 8-3.
- 8. Peeling force of cover tape: 0.1 to 1.0N.
- 9. The component will fall out naturally when cover tape is removed and set upside down.

Cover tap 165°~180° Career tape

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#### 8-5.Reel Specification



#### n the case of Φ180 Reel (3,000 pcs max, every 1,000 pcs)

Symbol	А	В	С	D
Dimension	φ180 +0/-3	φ60 +1/-0	φ13±0.2	φ21±0.8
Symbol	E	W	t	
Dimension	2.0±0.5	9±1	2.0±0.5	

(Unit : mm)

m)

#### In the case of Φ330 Reel (10,000 pcs max, every 1,000 pcs)

Symbol	А	В	С	D			
Dimension	φ330 <del>±</del> 2.0	φ100±1.0	φ13 <del>±</del> 0.2	φ21±0.8			
Symbol	E	W	t				
Dimension	2.0±0.5	9.5±0.5	2.2±0.1				

(Unit : m

### 9. Environmental requirements After following test, frequency shall not change more than $\pm 10 \times 10^{-6}$ And CI, $\pm 20\%$ or 5 $\Omega$ of large value. 9.1 Resistance to Shock Test condition Natural dropped from height 100cm onto hard wood board in 3 times 9.2 Resistance to Vibration Test condition : 10 - 55 - 10 Hz frequency Amplitude : 1.5mm Cycle time : 15 minutes Direction : X,Y,Z (3direction),2 h each. 9.3 Resistance to Heat Test condition The quartz crystal unit shall be stored at a temperature of +85±2°C for 500 h. Then it shall be subjected to standard atmospheric conditions for 1 h, after whichi measurement shall be made. 9.4 Resistance to Cold Test condition The quartz crystal unit shall be stored at a temperature of -40 $\pm$ 2°C for 500 h. Then it shall be subjected to standard atmospheric conditions for 1 h, after whichi measurement shall be made. 9.5 Thermal Shock Test condition The quartz crystal unit shall be subjected to 500 succesive change of temperature cycles , each as shown in table below, Then it shall be subjected to standard atmospheric conditions for 1h, after which measurements shall be made. : -40±2°C (30min.) to +25±2°C (5min.) Cycle to $+85\pm2^{\circ}C$ (30min.) to $+25\pm2^{\circ}C$ (5min.)

9.6	Resistance to Moisture	Test condition The quartz crystal unit shall be stored at a temperature of +60±2°C wich relative humidity of 90% to 95% for 240 h. Then it shall be subjected to standard atmospheric conditions for 1h, after which measurements shall be made

9.7 Soldering condition

1.) Material of solder

Kind … lead free solder paste

Melting point ··· +220±5°C

2.) Reflow temp.profile

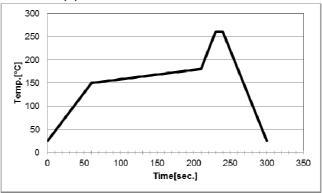
ne[sec]
(typ.)
(max.)
(max.)

Frequency shift :  $\pm 2$ ppm

3.) Hand Soldering +350°C 3 sec MAX

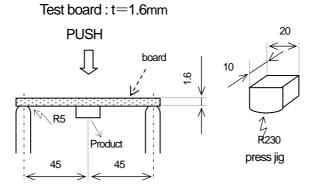
4.) Reflow Times 2 times

Reflow temp.profile



9.8 Intensity for bending in circuit board

Solder this product in center of the circuit board of  $40 \text{mm} \times 100 \text{mm}$ , and add the deflection of 3mm as the bottom figure.



UNIT : mm

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#### 10. Cautions for use

(1) Soldering upon mounting

There is a possibility to influence product characteristics when Solder paste or conductive glue comes in contact with product lid or surface.

#### (2) When using mounting machine

Please minimize the shock when using mounting machine to avoid any excess stress to the product.

(3) Conformity of a circuit

We strongly recommend to make sure that Negative resistance (Gain) of IC is designed to be 5 times the ESR (Equivalent Series Resistance) of crystal unit.

#### 11. Storage conditions

Please store product in below conditions, and use within 6 months. Temperature +18 to +30°C, and Humidity of 20 to 70 % in the packaging condition.

#### 12. Manufacturing location

Kyocera Crystal Device Corporation / Japan(Yamagata) Kyocera Crystal Device Corporation Shiga Yohkaichi Plant / Japan(Shiga) Kyocera Crystal Device (Thailand) Co., Ltd / Thailand(Lamphun)

#### 13. Quality Assurance

To be guaranteed by Kyocera Crystal Device Quality Assurance Division

#### 14. Quality guarantee

In case when Kyocera Crystal Device Corporation rooted failure occurred within 1year after its delivery, substitute product will be arranged based on discussion. Quality guarantee of product after 1year of its delivery is waivered.

#### 15. Others

In case of any questions or opinions regarding the Specification, please have it in written manner within 45 days after issued date.